

## Jason Bissias

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January 2026

Lubbock, TX

### **Education:**

Texas Tech University; M.S. in Electrical Engineering

Specialization topics: Semiconductor physics, process engineering, device simulation.

January 2025 through May 2026

GPA: 3.656/4.0

Texas Tech University; B.S. in Electrical Engineering, with minor in Computer Science

Specialization topics: VLSI, process engineering, semiconductor physics.

August 2021 through December 2024

GPA: 3.589/4.0

### **Certifications:**

FE in Electrical and Computer Engineering

As of September 2025

### **Selected work experience:**

Texas Tech University; Graduate Research Assistant

Researched InGaAs and wide-bandgap semiconductor device physics through physical and simulated measurements under various conditions, with auxiliary responsibilities being in managing lab space and lecturing in semiconductor physics courses.

January 2025 to Present

Texas Tech University; Undergraduate Teaching Assistant

Teaching assistant for semiconductor physics class, including assisting students and giving lectures.

August 2024 through December 2024

Texas Tech University; Undergraduate Research Assistant

Studied and contributed to research on GaN device structures.

January 2024 through May 2024

IT Help Central; Student Assistant

Provided technical assistance for TTU students and faculty.

May 2023 through September 2023

### **Skills:**

- Manual semiconductor parameter measurements (DC I-V, C-V)
- Manual wire bonding (Ball-to-wedge, wedge-to-wedge)
- Electronic device simulators (nextnano, Silvaco TCAD, Cadence Virtuoso, LTspice)
- Computer and chip architectures
- Programming (C/C++, Python, MATLAB, Verilog, Assembly)
- Office productivity suites (Microsoft Office, LibreOffice, Google Workspace)
- Lecturing experience
- Creative problem-solving
- Trilingual (English, Greek, French)
- Supervising experience